

	Type	Hits	Search Text	DBs
1	IS&R	1268	(336/200).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	544	substrate and ((336/200).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	380	conductor\$1 and (substrate and ((336/200).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	199	(end\$1 with connect\$2) and (conductor\$1 and (substrate and ((336/200).CCLS.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	1622	substrate and conductor\$1 and inductor and (end\$1 with connect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	1436	substrate and conductor\$1 and inductor and (end\$1 with connect\$3) and (insulat\$3 or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	478	substrate and conductor\$1 and inductor and (end\$1 with connect\$3) and (insulat\$3 or dielectric) and spiral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	27376	inductor.ti. or inductive.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	2148	substrate and (inductor.ti. or inductive.ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	254	lead and (substrate and (inductor.ti. or inductive.ti.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	570	substrate and (inductor.ti. or inductive.ti.) and spiral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	50	substrate and (inductor.ti. or inductive.ti.) and spiral and (conductor\$1 winding\$1) and (end\$1 with connect\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	306	substrate and (inductor.ti. or inductive.ti.) and spiral and (conductor\$1 winding\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	223	substrate and (inductor or inductive) and spiral and (conductor\$1 winding\$1) and (multi adj (level layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	326	substrate and (conductor\$1 winding\$1) and inductor and (end\$1 with connect\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	182	336/200.ccls. and substrate and ((multi adj (layer level)) or stack\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

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17	BRS	3803	(inductor or inductive) and substrate and ((multi adj (layer level)) or stack\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	BRS	2248	(inductor or inductive) and substrate and ((multi adj (layer level)) or stack\$2) and (conductor\$1 winding\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	BRS	1144	(inductor or inductive) and substrate and ((multi adj (layer level)) or stack\$2) and ((conductor\$1 winding\$1) with connect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	BRS	68	(inductor.ti. or inductive.ti.) and substrate and ((multi adj (layer level)) or stack\$2) and ((conductor\$1 winding\$1) with connect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	137	(inductor.ti. or inductive.ti.) and substrate and ((multi adj (layer level)) or stack\$2) and ((coil spiral conductor\$1 winding\$1) with (connect\$3 or interconnect\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	57	(inductor or inductive) and substrate and ((multi adj (layer level)) or stack\$2) and ((coil spiral conductor\$1 winding\$1) with (connect\$3 or interconnect\$3)) and (lead adj wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
23	BRS	5	(inductor.ti. or inductive.ti.) and substrate and (level\$1 or layer\$1 or stack\$2) and ((coil spiral conductor\$1 winding\$1) with (connect\$3 or interconnect\$3)) and (lead adj wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
24	BRS	140	(inductor.ti. or inductive.ti.) and substrate and (level\$1 or layer\$1 or stack\$2) and ((coil spiral conductor\$1 winding\$1) with (connect\$3 or interconnect\$3)) and hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
25	BRS	1268	336/200.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
26	BRS	376	substrate and (level\$1 or layer\$1 or stack\$2) and ((coil spiral conductor\$1 winding\$1) with (connect\$3 or interconnect\$3)) and 336/200.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB